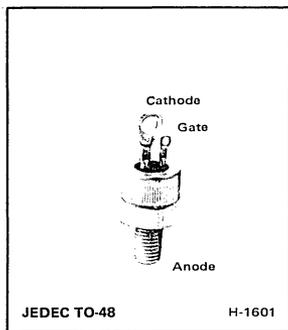


35-A Silicon Controlled Rectifiers

For Inverter Applications



Features:

- ▣ Fast turn-off time — 10 μ s max.
- ▣ High di/dt and dv/dt capabilities
- ▣ Shorted-emitter gate-cathode construction . . . contains an internally diffused resistor between gate and cathode
- ▣ Low thermal resistance
- ▣ Center gate construction . . . provides rapid uniform gate-current spreading for faster turn-on with substantially reduced heating effects

These RCA types are all-diffused, silicon controlled rectifiers designed for high-frequency power-switching applications such as inverters, switching regulators, and high-current pulse

applications. These types may be used at frequencies up to 25 kHz.

		2N3654	2N3655	2N3656	2N3657	2N3658	S7432M	
MAXIMUM RATINGS, Absolute-Maximum Values:								
*NON-REPETITIVE PEAK REVERSE VOLTAGE:^o								
Gate Open	V_{RSOM}	75	150	300	400	500	700	V
NON-REPETITIVE PEAK OFF-STATE VOLTAGE:^o								
Gate Open	V_{DSOM}	75	150	300	400	500	700	V
*REPETITIVE PEAK REVERSE VOLTAGE:^o								
Gate Open	V_{RROM}	50	100	200	300	400	600	V
*REPETITIVE PEAK OFF-STATE VOLTAGE:^o								
Gate Open	V_{DROM}	50	100	200	300	400	600	V
ON-STATE CURRENT:								
$T_C = 40^\circ\text{C}$, conduction angle = 180° :								
RMS	$I_T(\text{RMS})$			35				A
* Average	$I_T(\text{AV})$			25				A
*PEAK SURGE (NON-REPETITIVE) ON-STATE CURRENT:								
For one full cycle of applied principal voltage								
60 Hz (sinusoidal)	I_{TSM}			180				A
*RATE OF CHANGE OF ON-STATE CURRENT:								
$V_D = V_{DROM}$, $I_{GT} = 200\text{ mA}$, $t_r = 0.1\ \mu\text{s}$ (See Fig. 15)	di/dt			400				A/ μs
FUSING CURRENT (for SCR protection):								
$T_J = -65$ to 120°C , $t = 1$ to 8.3 ms	I^2t			165				A ² s
*GATE POWER DISSIPATION:^o								
Peak Forward (for 10 μs max., See Fig. 7)								
Average (averaging time = 10 ms max.)	P_{GM} $P_{G(\text{AV})}$			40 1				W W
*TEMPERATURE RANGE:^o								
Storage	T_{stg}			-65 to 150				$^\circ\text{C}$
Operating (Case)	T_C			-65 to 120				$^\circ\text{C}$
TERMINAL TEMPERATURE (During soldering):								
For 10 s max. (terminals and case)	T_T			225				$^\circ\text{C}$
STUD TORQUE:								
Recommended	τ_s			35				in-lb
Maximum (DO NOT EXCEED)				50				in-lb

^o In accordance with JEDEC registration data format (JS-14, RDF-1) filed for the JEDEC (2N series) types.

^o These values do not apply if there is a positive gate signal. Gate must be open or negatively biased.

^o Any product of gate current and gate voltage which results in a gate power less than the maximum is permitted.

^o For temperature measurement reference point, see Dimensional Outline.

ELECTRICAL CHARACTERISTICS

At Maximum Ratings Unless Otherwise Specified and at Indicated Case Temperature (T_C)

CHARACTERISTIC	SYMBOL	LIMITS			UNITS
		FOR ALL TYPES Except as Specified			
		MIN.	TYP.	MAX.	
* Peak Off-State Current: (Gate open, $T_C = 120^\circ\text{C}$) Forward Current (I_{DOM}) at $V_D = V_{DROM}$ Reverse Current (I_{ROM}) at $V_R = V_{RROM}$ 2N3654, 2N3655, 2N3656, S7432M 2N3657 2N3658	I_{DOM} or I_{ROM}	—	—	6 5.5 4	mA
* Instantaneous On-State Voltage: $i_T = 25\text{ A (peak), } T_C = 25^\circ\text{C}$	V_T	—	—	2.05	V
* Instantaneous Holding Current: Gate open, $T_C = 25^\circ\text{C}$ $T_C = -65^\circ\text{C}$	I_{HO}	—	75 150	150 350*	mA
* Critical Rate of Rise of Off-State Voltage: $V_D = V_{DROM}$, exponential voltage rise, Gate open, $T_C = 120^\circ\text{C}$ (See Fig. 16)	dv/dt	200	—	—	V/ μs
DC Gate Trigger Current: $V_D = 6\text{ V (dc), } R_L = 4\ \Omega, T_C = 25^\circ\text{C}$ $V_D = 6\text{ V (dc), } R_L = 2\ \Omega, T_C = -65^\circ\text{C}$	I_{GT}	—	80 150	180 500*	mA
DC Gate Trigger Voltage: $V_D = 6\text{ V (dc), } R_L = 4\ \Omega, T_C = 25^\circ\text{C}$ $V_D = V_{DROM}, R_L = 200\ \Omega, T_C = 120^\circ\text{C}$ $V_D = 6\text{ V (dc), } R_L = 2\ \Omega, T_C = -65^\circ\text{C}$	V_{GT}	— 0.25*	1.5 — 2	3 — 4.5*	V
* Circuit Commutated Turn-Off Time: (Rectangular Pulse) $V_{DX} = V_{DROM}, i_T = 10\text{ A, pulse duration} = 50\ \mu\text{s,}$ $dv/dt = 200\text{ V}/\mu\text{s, } -di/dt = -5\text{ A}/\mu\text{s, } I_{GT} = 200\text{ mA,}$ $V_{RX} = 15\text{ V min., } V_{GK} = 0\text{ V (at turn-off), } T_C = 120^\circ\text{C}$ (See Figs. 19 & 20)	t_q	—	—	10	μs
* Circuit Commutated Turn-Off Time: (Sinusoidal Pulse) $V_{DX} = V_{DROM}, i_T = 100\text{ A, pulse duration} = 2\ \mu\text{s, } dv/dt =$ $200\text{ V}/\mu\text{s, } V_{RX} = 30\text{ V min., } V_{GK} = 0\text{ V (at turn-off)}$ $T_C = 115^\circ\text{C}$ (See Figs. 17 & 18)	t_q	—	—	10	μs
* Thermal Resistance Junction-to-Case: Steady-State	$R_{\theta-JC}$	—	—	1.7	$^\circ\text{C}/\text{W}$

* In accordance with JEDEC registration data format (JS-14, RDF-1) filed for the JEDEC (2N-series) types.

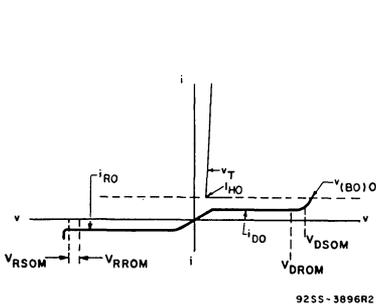


Fig. 1 — Principal voltage-current characteristic.

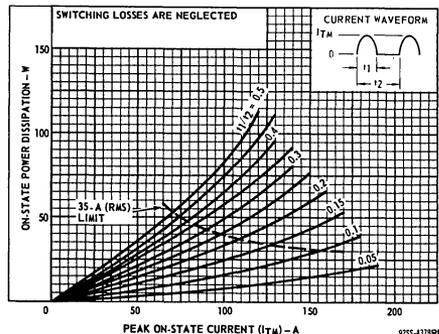


Fig. 2 — Power dissipation vs. peak on-state current.

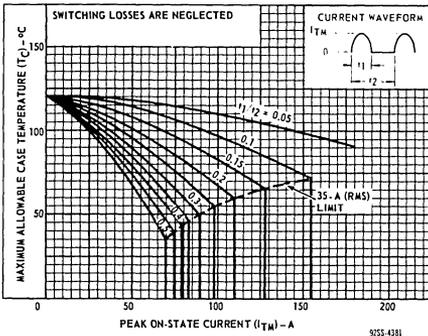


Fig. 3 - Maximum allowable case-temperature vs. peak on-state current.

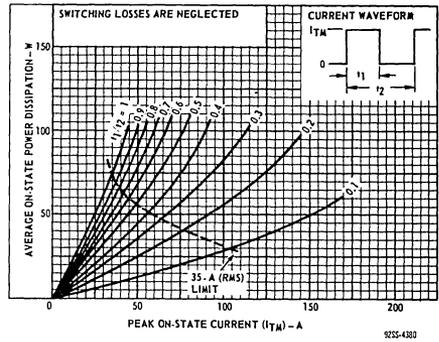


Fig. 4 - Power dissipation vs. peak on-state current.

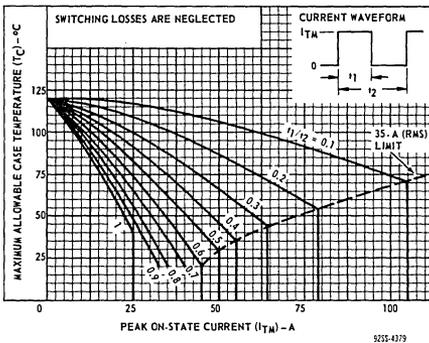


Fig. 5 - Maximum allowable case-temperature vs. peak on-state current.

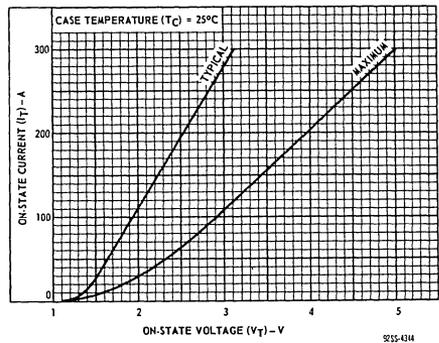


Fig. 6 - Variation of on-state current with on-state voltage.

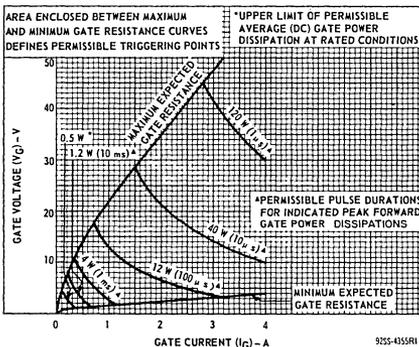


Fig. 7 - Typical forward-biased gate characteristics.

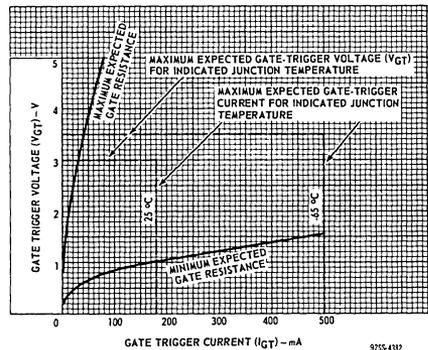


Fig. 8 - Typical gate-trigger characteristics.

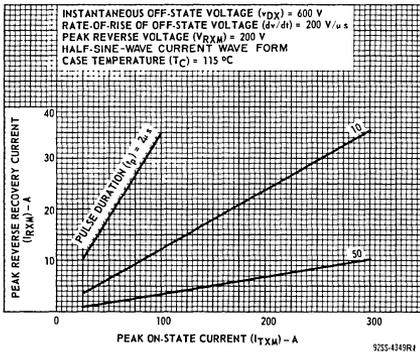


Fig. 9 — Typical variation of peak reverse-recovery current with peak on-state current (half-sine-wave pulse).

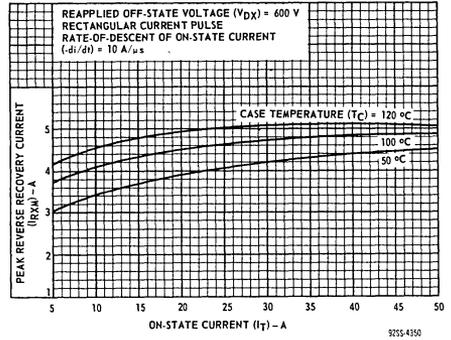


Fig. 10 — Typical variation of peak reverse-recovery current with on-state current (rectangular pulse).

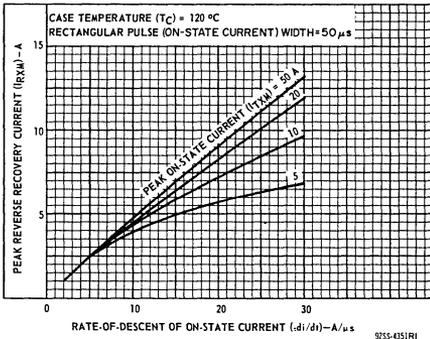


Fig. 11 — Typical variation of peak reverse-recovery current with rate-of-descent of on-state current (rectangular pulse).

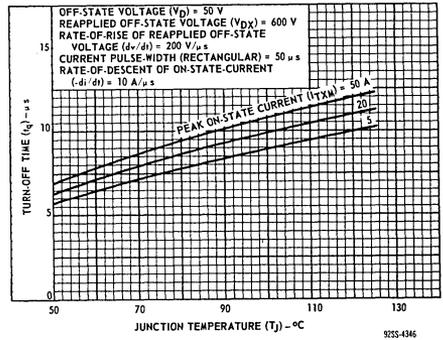


Fig. 12 — Typical variation of turn-off time with junction temperature (rectangular pulse).

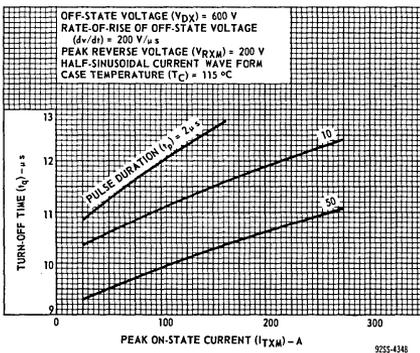


Fig. 13 — Typical variation of turn-off time with peak on-state current (half-sine-wave pulse).

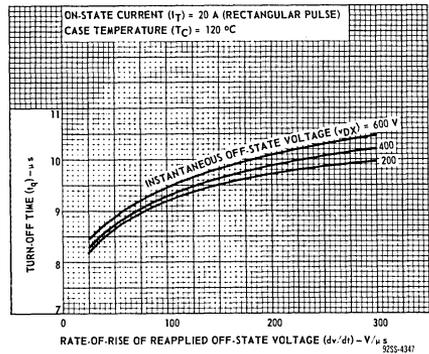


Fig. 14 — Typical variation of turn-off time with rate-of-rise of reapplied off-state voltage (rectangular pulse).

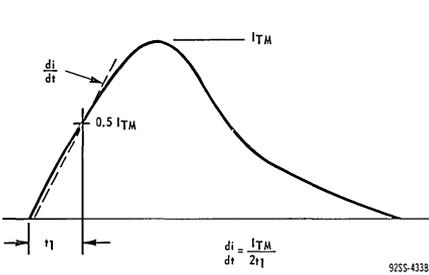


Fig. 15 - Rate-of-change of on-state current with time (defining di/dt).

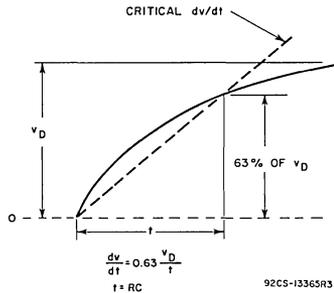


Fig. 16 - Rate-of-rise of off-state voltage with time (defining dv/dt).

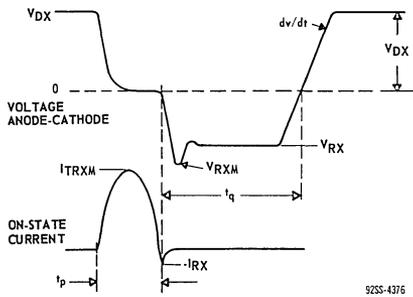


Fig. 17 - Relationship between off-state voltage, reverse voltage, on-state current, and reverse current showing reference points for specification of turn-off time (t_q), half-sine-wave pulse.

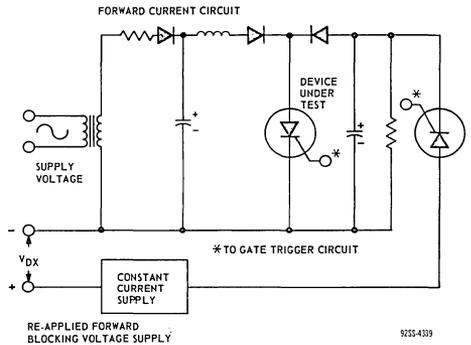


Fig. 18 - Circuit used to measure turn-off time (t_q), half-sine-wave pulse.

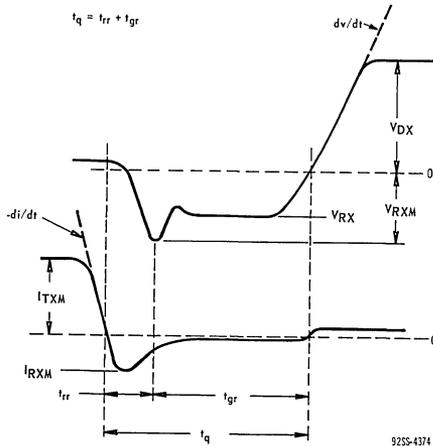


Fig. 19 - Relationship between off-state voltage, reverse voltage, on-state current, and reverse current showing reference points defining turn-off time (t_q), rectangular pulse.

